

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-18. (canceled).

19. (currently amended) A semiconductor light emitting device comprising a support plate; a light-reflective reflector having a reflector block which is mounted on the support plate or integrally formed with the support plate, the reflector being formed with a hole upwardly expanding; a semiconductor light emitting element mounted on the support plate within the hole of the reflector; a first wiring conductor electrically connected to one electrode of the light emitting element; a second wiring conductor electrically connected to the other electrode of the light emitting element through a lead wire;

~~wherein the reflector has a notch which passes through the reflector block between the hole and an outer side wall and between the light emitting element and wiring conductor block of the reflector has a notch to extend downwardly from an upper surface of the reflector in the direction toward the second wiring conductor from the light emitting element to communicate the hole with an outside of the reflector block;~~

~~the lead wire passes through the notch and strides over the reflector to electrically connect the light emitting element and the second wiring conductor.~~

20-21. (canceled).

22. (new) A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with an upwardly diverging hole; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; and a heat-resistible plastic encapsulant formed of opaque or semi-transparent resin for sealing at least an outer periphery of the reflector, an upper surface of the support plate, each inner end of the first and second wiring conductors;

wherein said plastic encapsulant is formed by injecting a liquid resin into a cavity of a forming mold under the condition of the support plate and the reflector clamped between upper and lower mold halves of the forming mold to form an opening at the top of said plastic encapsulant; and

said opening upwardly exposes the hole and an upper surface of the reflector outside of said plastic encapsulant.

23. (new) The semiconductor light emitting device of claim 22, wherein the support plate is formed of a metallic material having the thermal conductivity equal to or more than 190 kcal/mh°C.

24. (new) The semiconductor light emitting device of claim 22, wherein the plastic encapsulant is formed of black epoxy resin.

25. (new) The semiconductor light emitting device of claim 22, further comprising a lens formed of light-transmittable or transparent resin for covering upper surfaces of the reflector and plastic encapsulant.

26. (new) The semiconductor light emitting device of claim 25, further comprising a light-transmittable or transparent cover for covering a hole of the reflector.

27. (new) The semiconductor light emitting device of claim 26, wherein the lens is formed of a resin which has the melting point lower than that of the plastic encapsulant.

28. (new) A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; and a heat-resistible plastic encapsulant formed of opaque or semi-transparent resin for sealing at least an outer periphery of the reflector, an upper surface of the support plate, each

inner end of the first and second wiring conductors;

wherein said plastic encapsulant comprises an opening at the top thereof to upwardly expose the hole and an upper surface of the reflector outside of said plastic encapsulant, and a shoulder formed at a lower position than that of an upper surface of said plastic encapsulant in parallel to an upper surface of the reflector around the opening.

29. (new) A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; a light-transmittable or transparent cover attached on an upper surface of the reflector; and a heat-resistible plastic encapsulant formed of opaque or semi-transparent resin for sealing at least an outer periphery of the reflector, an upper surface of the support plate, side surfaces of the cover, each inner end of the first and second wiring conductors.

30. (new) A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting

element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; and a heat-resistible plastic encapsulant formed of opaque or semi-transparent resin for sealing at least an outer periphery of the reflector, an upper surface of the support plate, each inner end of the first and second wiring conductors;

wherein said plastic encapsulant is provided with an opening through which the hole and an upper surface of the reflector are exposed outside of said plastic encapsulant; and

an upper surface of said plastic encapsulant is in parallel to an upper surface of the reflector.

31. (new) A semiconductor light emitting device comprising a support plate; a light-reflective and electrically conductive reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector; and a plastic encapsulant for sealing at least an outer periphery of the reflector and an upper surface of the support plate;

wherein the reflector has a reflector block formed with the hole at the center, and a ledge extending outwardly from the reflector block and connecting to a wiring conductor; and

the ledge electrically connects the light emitting element and wiring conductor.

32. (new) The semiconductor light emitting device of claim

31, wherein the ledge is electrically connected to the wiring conductor via brazing metal.

33. (new) The semiconductor light emitting device of claim 31, wherein a lead wire electrically connects the semiconductor light emitting element and a flat area formed in the reflector.